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August 2018

ISL9R860P2, ISL9R860S3ST 8 A, 600 V, STEALTH™ Diode

Features

- Stealth Recovery trr = 28 ns (@ IF = 8 A)
- Max Forward Voltage, VF = 2.4 V (@ TC = 25°C)
- 600 V Reverse Voltage and High Reliability
- · Avalanche Energy Rated
- RoHS Compliant

Applications

- SMPS FWD
- · Hard Switched PFC Boost Diode
- · UPS Free Wheeling Diode
- Motor Drive FWD
- · Snubber Diode

Description

The ISL9R860P2, ISL9R860S3ST is a STEALTH™ diode optimized for low loss performance in high frequency hard switched applications. The STEALTH™ family exhibits low reverse recovery current (I_{RR}) and exceptionally soft recovery under typical operating conditions. This device is intended for use as a free wheeling or boost diode in power supplies and other power switching applications. The low I_{RR} and short ta phase reduce loss in switching transistors. The soft recovery minimizes ringing, expanding the range of conditions under which the diode may be operated without the use of additional snubber circuitry. Consider using the STEALTH™ diode with an SMPS IGBT to provide the most efficient and highest power density design at lower cost.

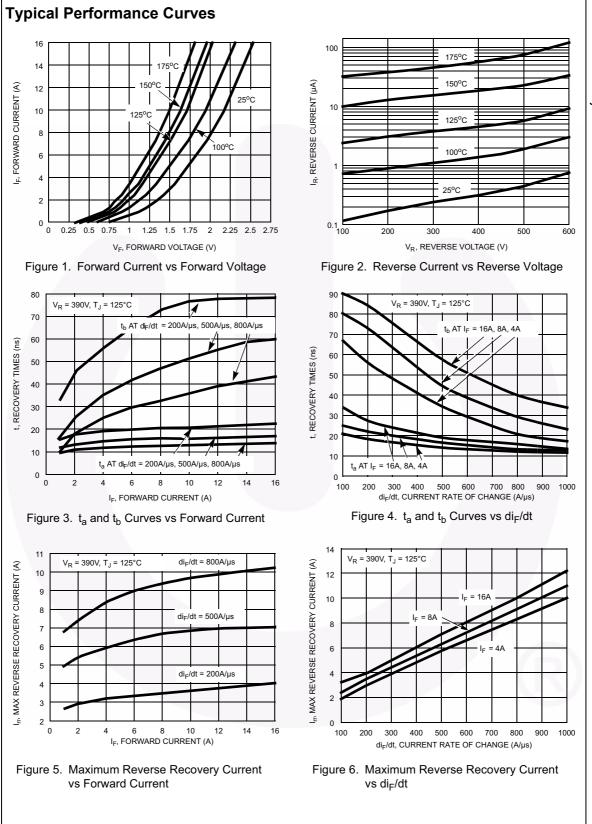
Package JEDEC TO-220AC-2L JEDEC TO-263AB(D²-PAK) CATHODE (FLANGE) N/C ANODE N/C ANODE

Device Maximum Ratings T_C= 25°C unless otherwise noted

Symbol	Parameter	Ratings	Unit
V _{RRM}	Peak Repetitive Reverse Voltage	600	V
V _{RWM}	Working Peak Reverse Voltage	600	V
V _R	DC Blocking Voltage	600	V
I _{F(AV)}	Average Rectified Forward Current (T _C = 147°C)	8	Α
I _{FRM}	Repetitive Peak Surge Current (20kHz Square Wave)	16	Α
I _{FSM}	Nonrepetitive Peak Surge Current (Halfwave 1 Phase 60Hz)	100	Α
P _D	Power Dissipation	85	W
E _{AVL}	Avalanche Energy (1 A, 40 mH)	20	mJ
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to 175	°C
T _L T _{PKG}	Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10s Package Body for 10s, See Techbrief TB334	300 260	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Part Num	ber	Top Mark	Package	Packing Me	Packing Method		Tap	Tape Width		Quantity
ISL9R860P2		R860P2	TO-220AC-2L	Tube		N/A		N/A		50
ISL9R860S3ST R860S3S TO-263AB(D ² -F		TO-263AB(D ² -PA	() Reel) Reel 13" Dia		24mm			800	
Electric	cal C	haracteri	Stics T _C = 25°C	unless otherwise	noted		•			
Symbol Parameter			Test Conditions			Min	Тур	Max	Unit	
Off State	Cha	racteristics				•				
		stantaneous Reverse Current		V _R = 600 V T _O	T _C =	= 25°C	_	-	100	μА
				, ,		= 125°C	-	-	1.0	mA
On State	Cha	racteristics								
		ntaneous Forwa		I _F = 8 A	T _C :	= 25°C	-	2.0	2.4	V
Г		instantaneous i orward voltage		T	T _C :	= 25°C = 125°C	-	1.6	2.0	V
Dynamic	Cha	racteristics								
C,		tion Capacitano		V _R = 10 V, I _F = 0	Λ			30	Ι.	pF
	1			VR - 10 V, IF - 0				00		Pi
Switchin	- -	aracteristic		_						
t _{rr} Reverse Recovery Time		$I_F = 1 A$, $di_F/dt =$			-	18	25	ns		
		<u></u>		$I_F = 8 A$, $di_F/dt =$	100 Α/μ	s, V _R = 30 V	-	21	30	ns
t _{rr}	-	everse Recovery Time		I _F = 8 A, di _F /dt = 200 A/μs, V _R = 390 V, T _C = 25°C		-	28	-	ns	
I _{rr}		verse Recovery Current				-	3.2	-	Α	
Q _{rr}		verse Recovery Charge					-	50	-	nC
t _{rr}		verse Recovery Time		I _F = 8 A, di _F /dt = 200 A/μs,		-	77	-	ns	
S	Softr	oftness Factor (t _b /t _a) everse Recovery Current				-	3.7	-		
I _{rr}	Reve			V _R = 390 V, T _C = 125°C			-	3.4	-	Α
Q _{rr}	Reve	erse Recovery C	Charge	710-1230			-	150	-	nC
t _{rr}	Reve	erse Recovery T	īme	I _F = 8 A,		-	53	-	ns	
S	Softr	ness Factor (t _b /t	(a)	$di_F/dt = 600 A/\mu s$,		-	2.5	-	
I _{rr}	Reve	erse Recovery C	Current	V _R = 390 V,		-	6.5	-	Α	
Q _{rr}	Reve	erse Recovery C	Charge	T _C = 125°C 195			-	nC		
dl _M /dt	Maxi	mum di/dt durin	ıg t _h				-	500	-	A/µs
	Cha	racteristics		•				•		•
HILEHIMA				T				1	1 75	°C/W
	Ther	mal Resistance	Junction to Case				-	-	1.75	C/VV
$\frac{R_{\theta JC}}{R_{\theta JA}}$			Junction to Case Junction to Ambien	t TO-220			-	-	62	°C/W



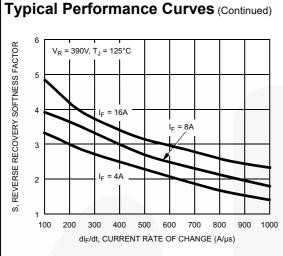


Figure 7. Reverse Recovery Softness Factor vs di_F/dt

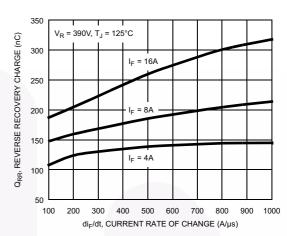


Figure 8. Reverse Recovery Charge vs di_F/dt

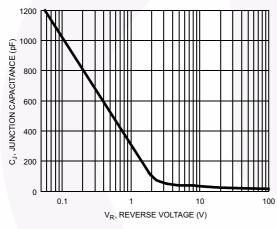


Figure 9. Junction Capacitance vs Reverse Voltage

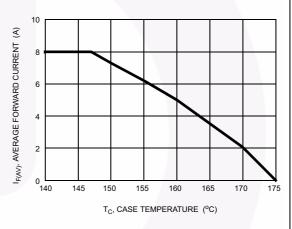


Figure 10. DC Current Derating Curve

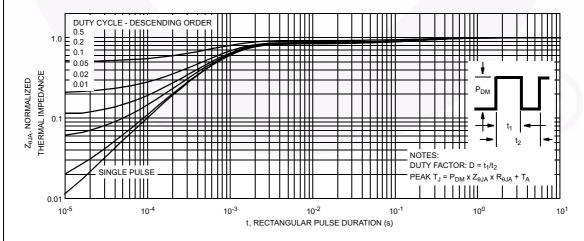
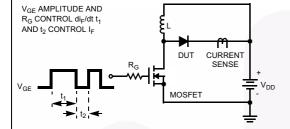


Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuits and Waveforms



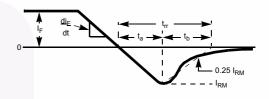
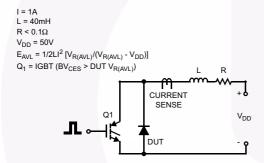


Figure 12. t_{rr} Test Circuit

Figure 13. t_{rr} Waveforms and Definitions



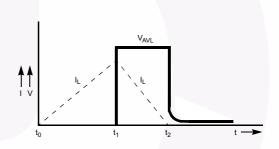


Figure 14. Avalanche Energy Test Circuit

Figure 15. Avalanche Current and Voltage Waveforms

Mechanical Dimensions

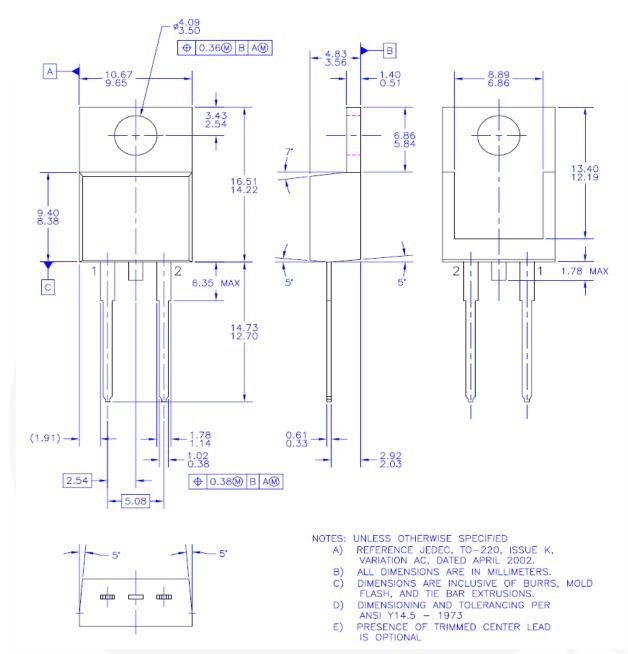


Figure 16. TO-220 2L - 2LD,TO220,JEDEC TO-220 VARIATION AC

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9.45 10.00 (6.40)1.78 MAX 3.80 (2.12)5.08 LAND PATTERN RECOMMENDATION UNLESS NOTED, ALL DIMS TYPICAL 5.08 → 0.25 M B AM 6.22 MIN 6.86 MIN 15.88 14.61 SEE DETA|L A NOTES: UNLESS OTHERWISE SPECIFIED A) ALL DIMENSIONS ARE IN MILLIMETERS. B) REFERENCE JEDEC, TO-263, VARIATION AB. C) DIMENSIONING AND TOLERANCING PER ANSI Y14,5M - 1994. D) LOCATION OF THE PIN HOLE MAY VARY GAGE PLANE (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE). E) LANDPATTERN RECOMMENDATION PER IPC 0.25 TO254P1524X482-3N F) FILENAME: TO263A02REV6 ○ 0.10 B 0.25 MAX (5.38) DETAIL A, ROTATED 90°

Figure 17. TO-263 2L (D2PAK) - 2LD,TO263, SURFACE MOUNT

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